

Subject to substantive adjustments

## Advanced Reflow Soldering Seminar Temperature Profiling and Troubleshooting



### March 29, 2023 in Timisoara, Romania

Today reflow soldering is still the most important connection technology for electronic assemblies. Our Advanced Reflow Soldering Seminar in Timisoara will focus on several important factors that influence the reflow soldering quality: What are the main aspects of an optimal soldering profile? How can you avoid common and special defect mechanisms? At an open round table, you can discuss your problems concerning reflow soldering with experts in this field. Rehm Thermal Systems invites you to broaden your horizon at this opportunity and welcomes you to Timisoara.

### March 29, 2023

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	09.30 a.m.	Welcome and Introduction Andreas Heltmann, Rehm Thermal Systems Basics of Reflow Profiling > Standards, Guidelines, Measurement Boards Dr. Paul Wild, Rehm Thermal Systems	1.15 p.m.	<ul> <li>Innovations of Rehm Thermal Systems</li> <li>New systems and options</li> <li>Andreas Heltmann, Rehm Thermal Systems</li> <li>Solder Paste Chemistry and its Behaviour during Reflow Soldering</li> <li>Solder paste chemistry caterial overview</li> <li>Main soldering issues and potential solutions Juraj Jánošík, Senju Metal Europe GmbH</li> </ul>
	09.45 a.m.		1.45 p.m.	
	10.15 a.m.	Measuring Board Preparation + Tips & Tricks > Preparation methods and rules > Thermal imaging camera, failures, tolerances Dr. Paul Wild, Rehm Thermal Systems		
			3.00 p.m.	Round Table Discussion and Coffee Break
11.15 a.m.		Coffee Break		All participants
	11.45 a.m.	<b>Reflow Profiling</b> > Influencing factors > Determination of temperature settings <i>Dr. Paul Wild, Rehm Thermal Systems</i>	3.45 p.m.	<b>Troubleshooting</b> <ul> <li>Whiskers and Black-Pad</li> <li>Wicking and Graping</li> <li>Voids</li> </ul> Dr. Paul Wild, Rehm Thermal Systems
	12.30 p.m.	Lunch break	5.00 p.m.	<b>End of seminar</b> Time for discussions and Get-Together

Attendance fees including beverage, lunch and seminar material 129,00 € per day >> registration before February 23, 2023 149,00 € per day >> registration after February 23, 2023

#### Register for both days and get an extra discount of 10% on the above attendance fee!





TECHNOLOGY ACADEMY Advanced Reflow Soldering Seminar

# Advanced Conformal Coating Seminar Conformal Coating





### March 30, 2023 in Timisoara, Romania

How do you ensure sustainable PCB protection for your electronic components? The coating technology in the electronics industry continues to advance. The wide range of materials and application methods are specially adapted to the assembly to be produced. It is not easy not to lose the overview here. On the second day of our seminar, you will learn about the basics and the diversity of coating technology and smart communication in line through to failure analysis of your coated product.

### March 30, 2023

09.30 a.m.	Welcome and Introduction Gianfranco Sinistra, Rehm Thermal Systems	11.45 a.m.	<b>Failure Analysis</b> <ul> <li>During the production process</li> <li>On the product</li> </ul> <i>Gianfranco Sinistra, Rehm Thermal Systems</i>
09.35 a.m.	<b>Basics of Coating Materials</b> > Which material for which application? <i>Gianfranco Sinistra, Rehm Thermal Systems</i>		
		12.45 p.m.	Lunch Break
10.30 a.m.	30 a.m. <b>Coffee Break</b>		Cleaning: Pro and Cons
10.45 a.m.	<b>Variety of Coating Technologies</b> > Different applications <i>Gianfranco Sinistra, Rehm Thermal Systems</i>		<ul> <li>Necessity in different environmental conditions</li> <li>Gianfranco Sinistra, Rehm Thermal Systems</li> </ul>
		2.30 p.m.	Line Connectivity - Smart Communications Gianfranco Sinistra, Rehm Thermal Systems
11.15 p.m.	Coffee Break		
·		3.30 p.m.	End of Seminar Time for Discussions and Get-Together

Attendance fees including beverage, lunch and seminar material

**129,00 €** per day >> registration **before** February 23, 2023 **149,00 €** per day >> registration **after** February 23, 2023

### Register for both days and get an extra discount of 10% on the above attendance fee!

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TECHNOLOGY ACADEMY Advanced Reflow Soldering Seminar

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Registration to the Advanced Reflow Soldering							
Vour portionation	□ March 20, 2022 □ March 20, 2022	EARLY BOOKING DISCOUNT					
Your participation 129,00 € per day	>> registration before February 23, 2023						
149,00 € per day							
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- » Return to Ms. Ina Haug by E-Mail: *i.haug@rehm-group.com*
- » Or register on our Website: <u>www.rehm-group.com/en/news/dates</u>

Location of the seminar is **HOTEL TIMISOARA, 300086 Marasesti Str. 1-3, Timisoara, Romania**. If you need an accommodation you can book a room from our contingent with the keyword.

Keyord: REHM TECHNOLOGY SEMINAR

Mrs. Teodora Munteanu | E-Mail: office@hoteltimisoara.ro Phone: +40 256 498852 | Web: www.hoteltimisoara.ro

The price for one single room is 70 € (Business room) per night incl. breakfast. The contingent is available until March 5, 2023.



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